PRINTED WIRING PRODUCTS
RESIN-COATED METAL TYPE
GENERAL EQUIPMENT REQUIREMENTS

1. GENERAL

1.001 This addendum supplements Section 800-610-162, Issue 1-D.

1.002 This addendum is issued to:

(a) Add references to requirements for rigid multilayer printed wiring boards.

(b) Correct typographical errors.

(c) Add requirements for soldering of surface-connected integrated circuits.

(d) Modify requirements for acceptance of lifted terminal areas.

The following change applies to Part 1 of the section:

(a) 1.05—added

1.05 Requirements for rigid multilayer printed wiring boards are covered in X-17815.

4. REQUIREMENTS FOR PRINTED WIRING ASSEMBLIES

The following changes apply to Part 4 of the section:

(a) 4.01—revised

(b) 4.11 (e)—added

(c) 4.18 (b)—revised

4.01 The requirements covered in Part 3 shall apply to the completed assembly except as modified below.

(a) A conductor path discontinuity is acceptable if repaired in accordance with 4.17.

(b) A lifted portion of a conductor path which exceeds 0.5 inch in length is not acceptable. When the lifted portion is 0.5 inch or less in length, it is acceptable if repaired in accordance with 4.18.

(c) A terminal area that is lifted 50 percent or less (judged visually) is acceptable, provided one of the following conditions is met:

(1) The component lead is clinched to the terminal area.

(2) The terminal area is repaired in accordance with 4.18.

4.11 (e) Solder fillets along the package leads of surface-connected integrated circuits [92-, 93-, or 94-type, 30-type gate, or similar integrated circuits of approximately the same (or smaller) size and lead configuration] shall meet one of the following requirements:

(1) Where there are fillets along both edges of the lead, the total length of the fillets shall be at least 0.100 inch.

(2) Where there is a fillet along only one edge of the lead, there shall be a continuous fillet for a distance of at least 0.100 inch.

4.18 (b) ***Missing:*** When a terminal area is completely lifted or is missing, it may be repaired as follows:

(1) Wrap at least one full turn of bare tinned copper wire (26AWG minimum) around the component lead. Lay the other end of the wire at least 0.13 inch along the conductor path and solder. Minimum spacing requirements shall not be violated.

(2) Cover the portion soldered to the conductor path with epoxy per (a).